

**Qualification Description:**

New Model Qualification for LOG112AID, Precision Logarithmic and log ratio amplifier.

Model:	<b>LOG112AID</b>	Assembly Site:	OSE-Taiwan
RA:	<b>8941</b>	Package Type:	SOIC
PA:	<b>3741</b>	Lead Count:	14
Date:	6/20/2002	Bond Wire Material:	Au
Die Name:	CIC03188	Bond Wire Diameter:	1.2
Die Size:	0.090 X 0.200	Lead Frame Material:	SSC
Mask Revision:	A	Lead Frame Finish:	Solder Plate
Wafer Fab Site:	TI-Tucson		
Process:	435G		
Technology:	Bipolar		
Passivation:	LTO/SiON 5kA/8kA		

HTOL assem/wafer/lot :	19865404	Latch Up assem/wafer/lot	N/A
HAST assem/wafer/lot :	N/A	ESD assem/wafer/lot	19865404
Autoclave assem/wafer/lot :	N/A	X-Ray assem/wafer/lot	19865404
Temp Cycle assem/wafer/lot :	N/A	MSL assem/wafer/lot	N/A

**Test Results:**

Test	Conditions	Readpoints	Sample Size	Defects	QBS Ref. Num.	QBS Results (SS/Rej)
Life Test	125°C	1008 hrs Hrs.	77	0		
HAST	85%RH, 33.5 psia, 100 Hrs.	100 Hrs.			1QTR02	713/0
Autoclave	121°C, 15psia, 100%RH,	96 Hrs.			1QTR02	711/0
Temp Cycle	-65°C to +150°C	500 cycles			1QTR02	792/0
ESD	HBM	500 volts	3	0		
	HBM	1000 volts	3	0		
	HBM	2000 volts	9	9		
	HBM	3000 volts	3	0		
	HBM	4000 volts	3	2		
	CDM	125 volts	3	0		
	CDM	250 volts	3	0		
	CDM	500 volts	3	0		
	CDM	1000 volts	3	0		
	CDM	1500 volts	3	0		
Elec. Charac. over Temp	PDS		75	0		
X-Ray			125	0		

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